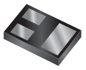
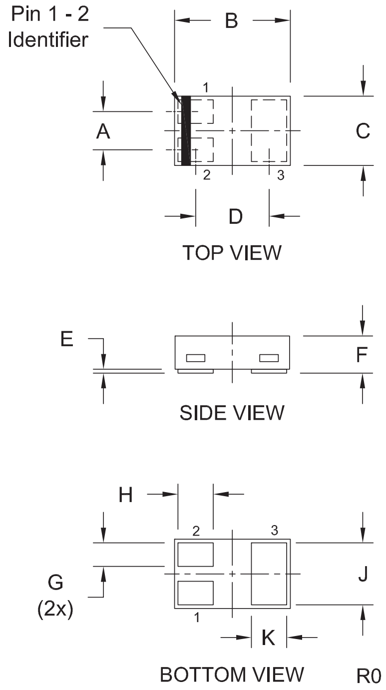
Package Details
SOT-883VL Case

Top View


Bottom View

Mechanical Drawing



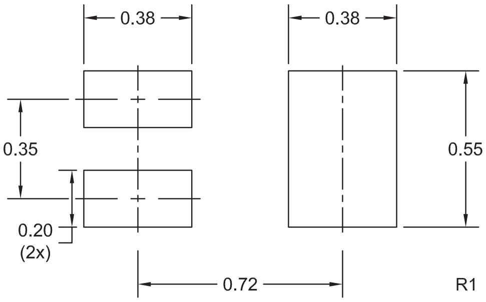
	DIMENSIONS			
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.014		0.35	
B	0.037	0.041	0.95	1.05
C	0.022	0.026	0.55	0.65
D	0.026		0.65	
E	0.000	0.002	0.00	0.05
F	0.012	0.013	0.30	0.32
G	0.004	0.008	0.10	0.20
H	0.008	0.012	0.20	0.30
J	0.018	0.022	0.45	0.55
K	0.008	0.012	0.20	0.30

SOT-883VL (REV:R0)

Part Marking:
Single Character Alpha/Numeric Code

Lead Code:
Reference individual device data sheet.

Mounting Pad Geometry (Dimensions in mm)



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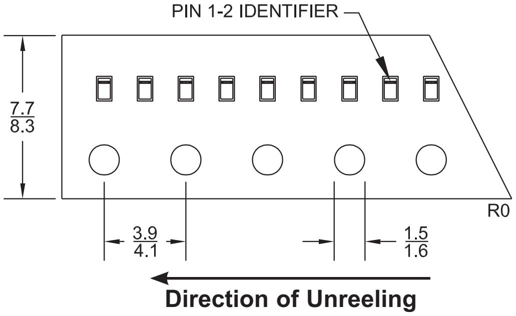
Package Details

SOT-883VL Case

Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 8mm



Devices are taped in
accordance with
Electronic Industries
Association Standard
EIA-481-D

Packaging Base

7” Reel = 8,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7”	9	72,000	9x9x5	23x23x13	3	2
	18	144,000	9x9x9	23x23x23	6	3
	40	320,000	21x9x9	53x23x23	13	6
	108	864,000	27x9x17	69x23x43	34	16

Ordering Information

- For devices taped and reeled on 7” reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

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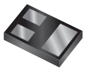
Material Composition Specification

SOT-883VL Case


Top View


Bottom View

Device average mass . . . . **0.614 mg**

Fluctuation margin . . . . **+/-10%**

Component	**Material**	**Material**		**Substance**	**CAS No.**	**Substance**		
		(%wt)	**(mg)**			**(%wt)**	**(mg)**	**(ppm)**
active device	doped Si	5.7%	0.035	Si	7440-21-3	5.7%	0.035	57,003
bond wire	gold	1.63%	0.01	Au	7440-57-5	1.63%	0.01	16,287
leadframe	Cu alloy	42.35%	0.26	Cu	7440-50-8	40.72%	0.25	407,166
				Ni	7440-02-0	1.29%	0.0079	12,866
				Si	7440-21-3	0.28%	0.0017	2,769
				Mg	7439-95-4	0.07%	0.0004	651
die attach	silver epoxy	0.9%	0.0055	epoxy resin	Proprietary	0.18%	0.0011	1,792
				Ag	7440-22-4	0.72%	0.0044	7,166
encapsulation*	EMC GREEN	49.02%	0.301	silica (fused)	60676-86-0	41.53%	0.255	415,309
				epoxy resin	29690-82-2	3.75%	0.023	37,459
				phenol resin	9003-35-4	1.3%	0.0080	13,029
				carbon black	1333-86-4	0.16%	0.001	1,629
				metal hydroxide	1309-42-8	2.28%	0.014	22,801
plating	Ni/Pd/Au	0.41%	0.0025	Ni	7440-02-0	0.36%	0.0022	3,583
				Pd	7440-05-3	0.03%	0.0002	326
				Au	7440-57-5	0.02%	0.0001	163

*EMC GREEN molding compound is Halogen-Free.

R0 (20-October 2014)